MC10H124

Quad TTL-to-MECL Translator With TTL Strobe Input

The MC10H124 is a quad translator for interfacing data and control signals between a saturated logic section and the MECL section of digital systems. The 10H part is a functional/pinout duplication of the standard MECL 10K family part, with 100% improvement in propagation delay, and no increase in power−supply current.

- Propagation Delay, 1.5 ns Typical
- Improved Noise Margin 150 mV
  (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K−Compatible
- Pb−Free Packages are Available*

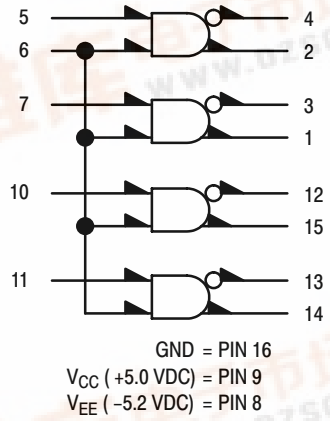
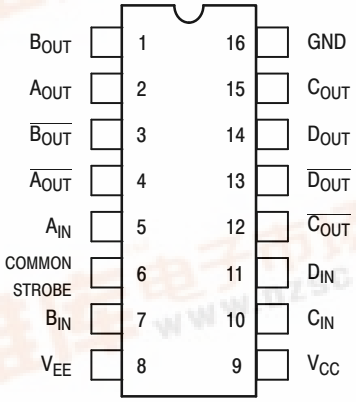


Figure 1. Logic Diagram



Pin assignment is for Dual−in−Line Package.
For PLCC pin assignment, see Table 1.

Figure 2. Pin Assignment

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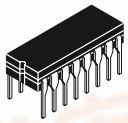
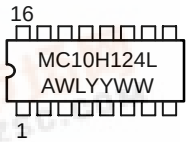
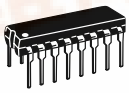
http://onsemi.com

MARKING DIAGRAMS

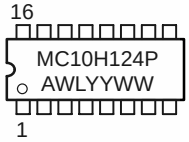


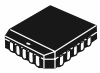
CDIP−16
L SUFFIX
CASE 620A



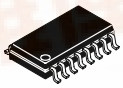


PDIP−16
P SUFFIX
CASE 648

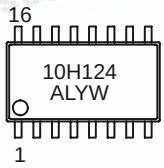




PLCC−20
FN SUFFIX
CASE 775



EIAJ−16
M SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Table 1. DIP CONVERSION TABLE

16−Pin DIL to 20−Pin PLCC

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

Table 2. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply (V_{CC} = 5.0 V)	−8.0 to 0	Vdc
V_{CC}	Power Supply (V_{EE} = −5.2 V)	0 to +7.0	Vdc
V_I	Input Voltage (V_{CC} = 5.0 V) TTL	0 to V_{CC}	Vdc
I_{out}	Output Current − Continuous − Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range − Plastic − Ceramic	−55 to +150 −55 to +165	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 3. ELECTRICAL CHARACTERISTICS (V_{EE} = −5.2 V ±5%, V_{CC} = 5.0 V ± 5.0%)

		0°		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
I_E	Negative Power Supply Drain Current	−	72	−	66	−	72	mA
I_{CCH} I_{CCL}	Positive Power Supply Drain Current	− −	16 25	− −	16 25	− −	18 25	mA
I_R	Reverse Current Pin 6 Pin 7	 − −	 200 50	 − −	 200 50	 − −	 200 50	μA
I_F	Forward Current Pin 6 Pin 7	 − −	 −12.8 −3.2	 − −	 −12.8 −3.2	 − −	 −12.8 −3.2	mA
$V_{(BR)in}$	Input Breakdown Voltage	5.5	−	5.5	−	5.5	−	Vdc
V_I	Input Clamp Voltage	−	−1.5	−	−1.5	−	−1.5	Vdc
V_{OH}	High Output Voltage	−1.02	−0.84	−0.98	−0.81	−0.92	−0.735	Vdc
V_{OL}	Low Output Voltage	−1.95	−1.63	−1.95	−1.63	−1.95	−1.60	Vdc
V_{IH}	High Input Voltage	2.0	−	2.0	−	2.0	−	Vdc
V_{IL}	Low Input Voltage	−	0.8	−	0.8	−	0.8	Vdc

1. Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50 Ω resistor to −2.0 V.

Table 4. AC CHARACTERISTICS

		0°		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t_{pd}	Propagation Delay	0.55	2.5	0.55	2.65	0.85	3.1	ns
t_r	Rise Time	0.5	1.5	0.5	1.6	0.5	1.7	ns
t_f	Fall Time	0.5	1.5	0.5	1.6	0.5	1.7	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

APPLICATIONS INFORMATION

The MC10H124 has TTL−compatible inputs and MECL complementary open−emitter outputs that allow use as an inverting/non−inverting translator or as a differential line driver. When the common strobe input is at the low−logic level, it forces all true outputs to a MECL low−logic state and all inverting outputs to a MECL high−logic state.

An advantage of this device is that TTL−level information can be transmitted differentially, via balanced twisted pair lines, to MECL equipment, where the signal can be received by the MC10H115 or MC10H116 differential line receivers. The power supply requirements are ground, +5.0 V, and −5.2 V.

ORDERING INFORMATION

Device	Package	Shipping†
MC10H124L	CDIP−16	25 Units/Rail
MC10H124P	PDIP−16	25 Units/Rail
MC10H124PG	PDIP−16 (Pb−Free)	25 Units/Rail
MC10H124FN	PLCC−20	46 Units/Rail
MC10H124FNG	PLCC−20 (Pb−Free)	46 Units/Rail
MC10H124FNR2	PLCC−20	1000 Tape & Reel
MC10H124M*	EIAJ−16 (Pb−Free)	50 Units/Rail
MC10H124MEL*	EIAJ−16 (Pb−Free)	2000 Tape & Reel

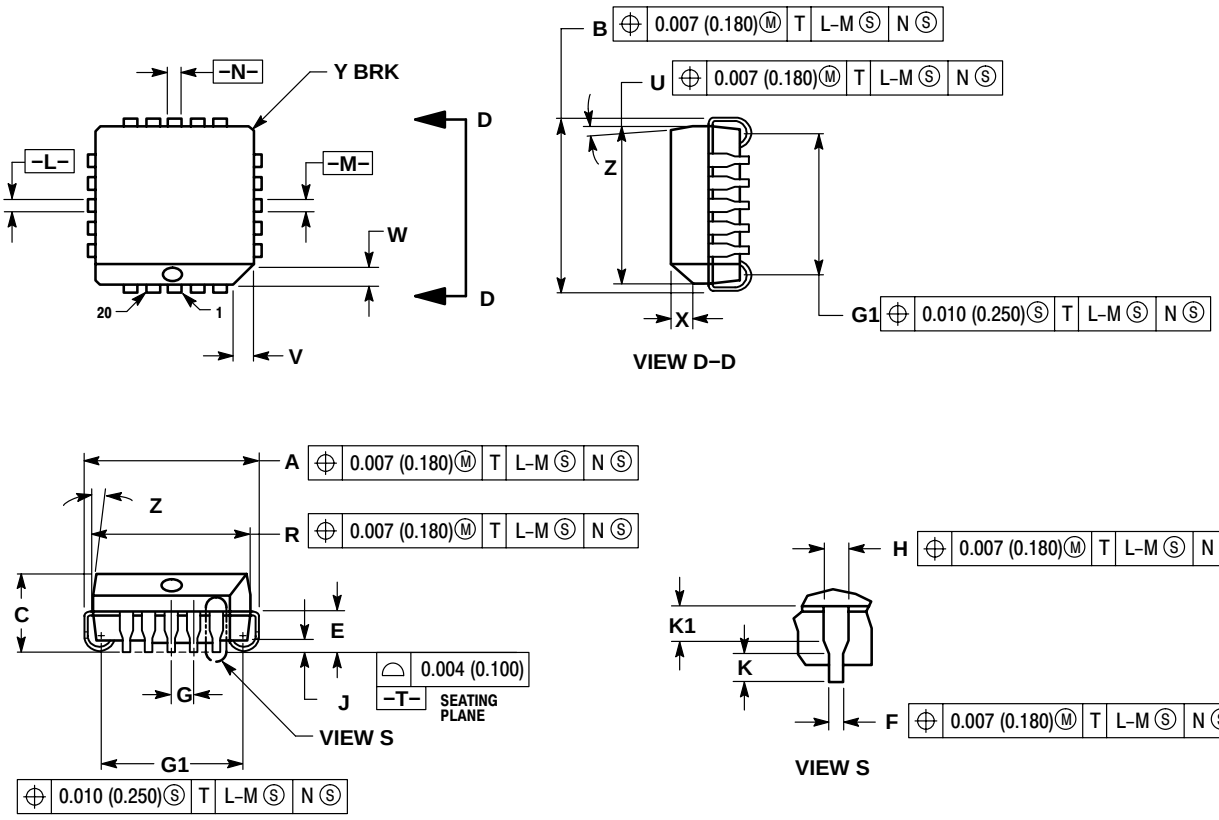
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This device is manufactured with a Pb−Free external lead finish only.

Resource Reference of Application Notes

AN1405/D − ECL Clock Distribution Techniques
AN1406/D − Designing with PECL (ECL at +5.0 V)
AN1503/D − ECLinPS™ I/O SPiCE Modeling Kit
AN1504/D − Metastability and the ECLinPS Family
AN1568/D − Interfacing Between LVDS and ECL
AN1642/D − The ECL Translator Guide
AND8001/D − Odd Number Counters Design
AND8002/D − Marking and Date Codes
AND8020/D − Termination of ECL Logic Devices
AND8066/D − Interfacing with ECLinPS
AND8090/D − AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

PLCC−20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775−02
ISSUE D

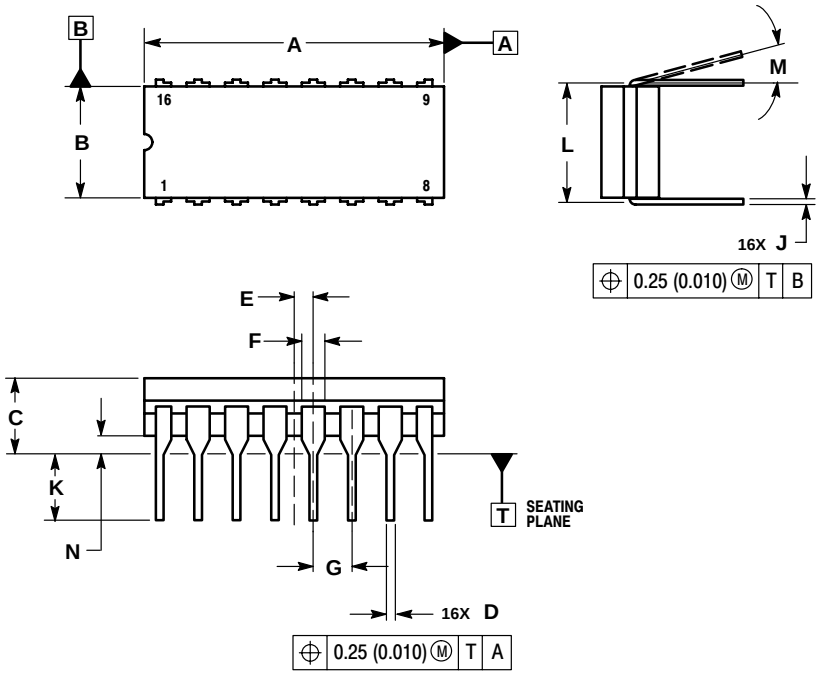


NOTES:
1. DATUMS −L−, −M−, AND −N− DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM −T−, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

PACKAGE DIMENSIONS

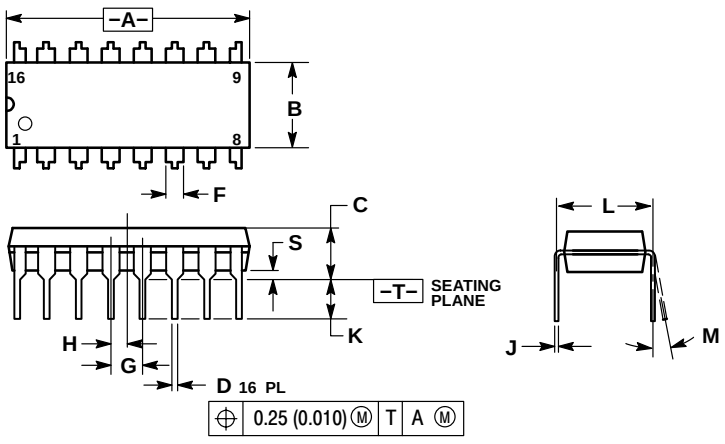
CDIP−16
L SUFFIX
CERAMIC DIP PACKAGE
CASE 620A−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
5 THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620−10.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

PDIP−16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648−08
ISSUE T



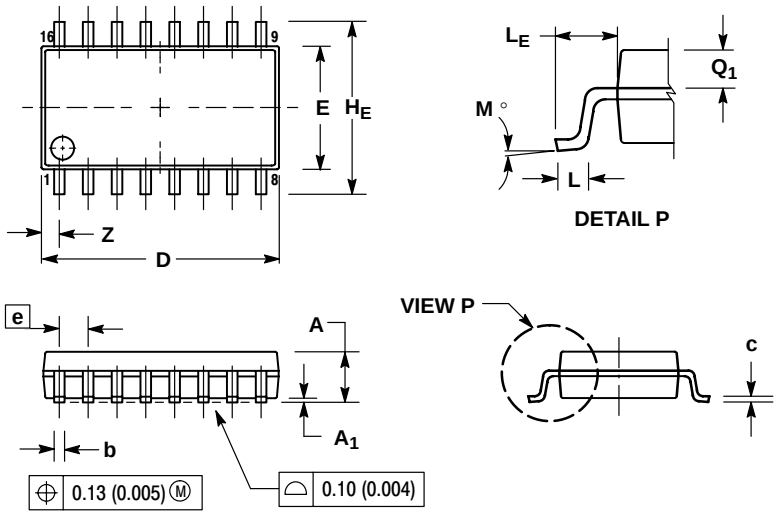
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

MC10H124

PACKAGE DIMENSIONS

EIAJ−16
M SUFFIX
16 PIN PLASTIC EIAJ PACKAGE
CASE 966−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	−−−	2.05	−−−	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	−−−	0.78	−−−	0.031

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PUBLICATION ORDERING INFORMATION

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